

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Chih-Lung LIN	03/24/2021
Jie-An LIN	03/24/2021
Ming-Yang DENG	03/24/2021
Chia-En WU	03/24/2021
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17237794
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NAME OF SUBMITTER:	JUSTIN KING

SIGNATURE:	/Justin King/
DATE SIGNED:	04/22/2021
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 3 source=da#page1.tif source=da#page2.tif source=da#page3.tif	

AU2006045/109-268EP-US1/NP-28432-US

Combined Declaration and Assignment for Patent Application

In Chinese/English

美國專利申請聲明以及美國專利轉讓

For the subject matter which is claimed and for which a patent is sought on the invention entitled:
專利申請權利要求的發明名稱如下:

PIXEL COMPENSATION CIRCUIT

I hereby declare that: As a below named inventor
我在此宣告：作為下述發明者

The specification of which is attached hereto unless the following box is checked 並將其說明書在此附上，除非以下方格已打叉：

was filed on 其發明已立 案于

as United States Application Number or PCT International Application Number 其美國申請號碼或 PCT 國際申請號碼為

The above-identified application was made or authorized to be made by me.
以上所提之申請案係由我撰寫或是在我的授權下所撰寫。

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.
我相信我是首創發明者或是首創共同發明者。

I hereby acknowledge that willful false statements made in this statement is punishable under 18 U.S.C. 1001 by fine or/and imprisonment of not more than five (5) years.

我了解，按照美國法規第十八節第一千零一項，任何蓄意偽造的聲明都可受到罰款和/或五年以下有期徒刑。

ASSIGNMENT**美國專利轉讓**

WHEREAS, I(we), the named inventor(s), whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR,
作為下述其郵遞地址的發明者，在此稱轉讓人

WHEREAS, [AU Optronics Corporation and 2. NATIONAL CHENG KUNG UNIVERSITY]
whose post office address is [NO. 1, LI-HSIN ROAD 2, SCIENCE-BASED INDUSTRIAL PARK HSIN-
CHU TAIWAN ROC and 2. NO. 1, TA-HSUEH ROAD, TAINAN CITY, TAIWAN, R.O.C.]
hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States and
its territorial possessions.

AU2006045/109-248EP-USI/NP-28432-US

DAI Optoelectrics Corporation and 2 NATIONAL CHING CHIANG UNIVERSITY [位於 NO. 1, LI-HSIN ROAD 2, SCIENCE-BASED INDUSTRIAL PARK HSIN-CHU TAIWAN R.O.C and 2, NO. 1, TA-HSUEH ROAD, TAINAN CITY, TAIWAN, R.O.C.], 在此經讓受人, 取得此發明在美國與其管轄境內之所有權利。

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), Assignor, by these presents do sell, assign and transfer unto said Assignee, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part, and renewal of said application, for the full term or terms for which the same may be granted, including all priority rights under any International Conventions.

特將此發明之權利, 標題, 專利權, 專利申請, 以及本發明案之所有在美國與管轄境內之所有權利, 包括任何專利申請案內之分支, 續案, 重新核對案, 包括任何國際公約所保障之優先權。

ASSIGNOR further covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

轉讓人將不會簽署任何與此轉讓案相悖之再轉讓, 販售, 或合資協議。

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNOR in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNOR's expense, to identify and communicate to ASSIGNEE or ASSIGNEE's request documents and information concerning the INVENTION that are within ASSIGNOR's possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance, litigation and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR's heirs, executors, administrators and other legal representatives.

轉讓人將無條件地同意任何法律上所要求與本發明有關之文件, 包括提交申請, 駁回答覆, 年費, 以及任何證明讓受人擁有本發明之文件。在讓受人之要求下, 轉讓人也將無條件地協助讓受人, 提供讓受人轉讓人所持有之發明文件資料, 並提供讓受人步是讓受人之法定繼承人在法律上所要求之照顧答覆, 授權訴訟相關協助。

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE's sole use and benefit; and for the use and benefit of ASSIGNEE's legal representatives and successors, to the full and of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made. 轉讓人在此要求美國專利商標局在核對本發明專利時, 根據以上所陳述讓受人之申請以及本發明案之所有在美國之相關權利, 核發於讓受人。

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